

Method for Applying a Bonding Layer

Abstract

The invention relates to a method for applying a bonding layer that consists of a basic layer and a protective layer on a substrate with the following method steps:

- Application of an oxidizable basic material as a basic layer on a bonding side of the substrate,
- At least partial covering of the basic layer with a protective material that is at least partially dissolvable in the basic material as a protective layer.

In addition, the invention relates to a corresponding substrate.

Figure 5a.